5 Ø / Descriptions

Ý‰ ˚ Ö8 â k F g 9 y < d < k 3 g v y ’ k V ” 9 3 ’ , / xo
Surface Mount Superfast Recovery Rectifier, Reverse Voltage: 50 to 600V, Forward Current: 3A, SMAF thin package.

/“ / Features

ì łdý / Ì k Ý‰ F g ˚ Ö k ‘ ‘ , (8 U . 9 6 X + ; k 9 n µÉx k)í D
}o
Glass Passivated Chip Junction ¨Superfast reverse recovery time ¨Lead free in comply with EU R 2HS 2011/65/EU directives ¨ For surface mounted applications,HF Product.

— ÷ / Applications

%† " (o
General purpose.

ˆ W] Ô / Equivalent Circuit



Û- æ / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode



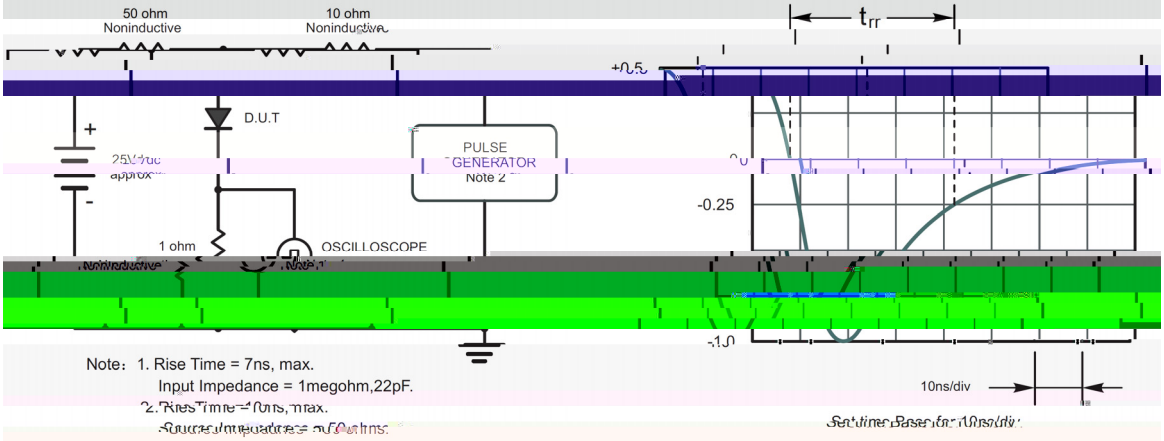
, M V / Marking

- ~ “ ¢o
See Marking Instructions.

	@	Z	Rating	% y

Ô? d ¢ / Electrical Characteristic Curve

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note：1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

Fig.1 Forward Current Derating Curve

Fig.2 Typical Reverse Characteristics

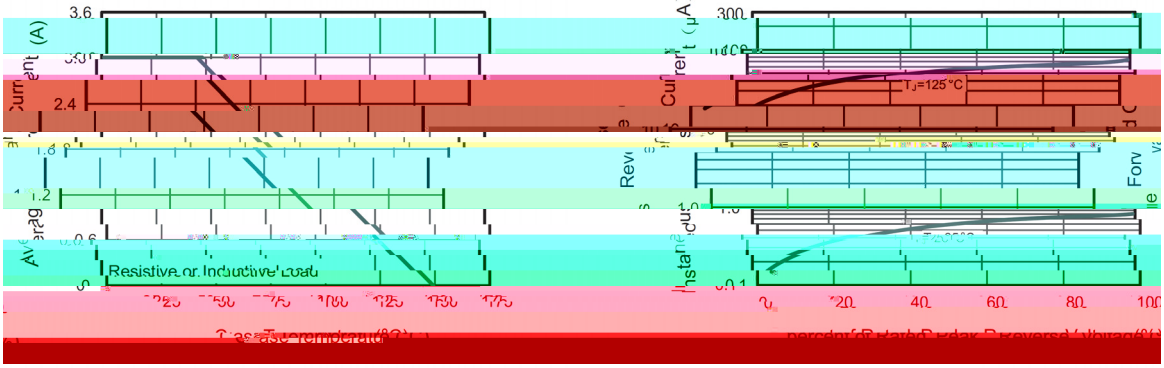
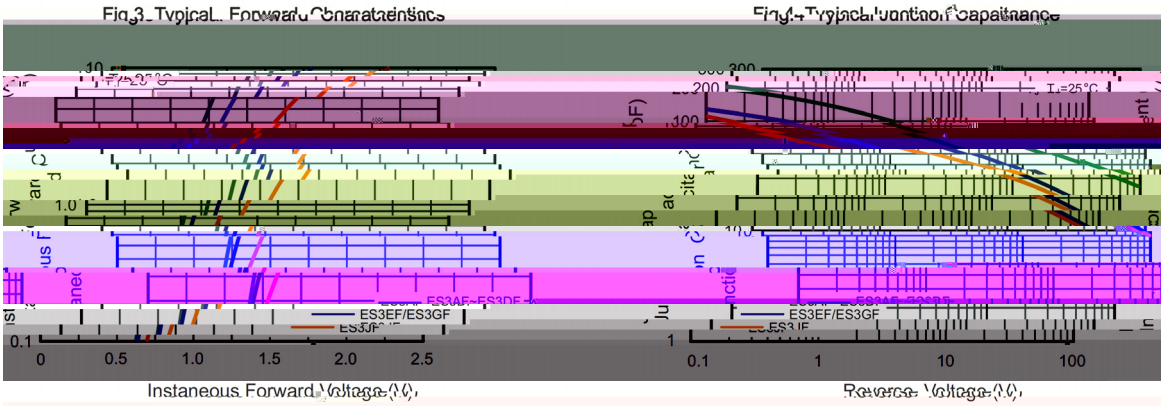


Fig.3 Typical Forward Characteristics

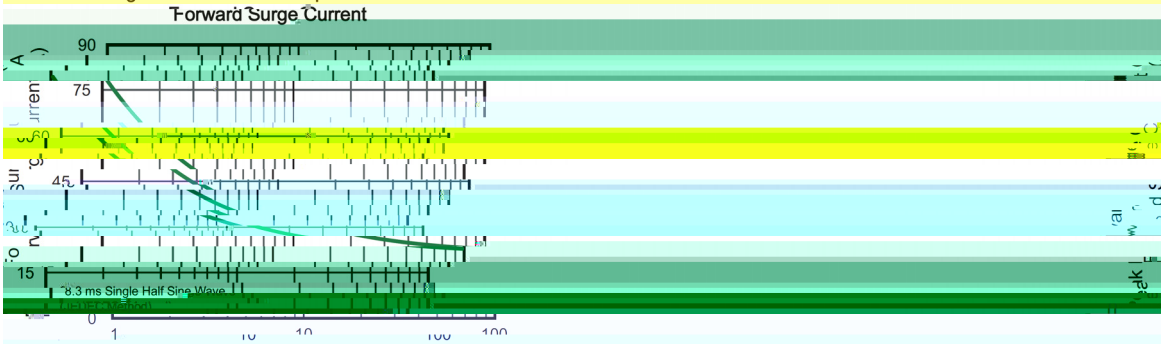
Fig.4 Typical Junction Capacitance



Instaneous Forward Voltage (V)

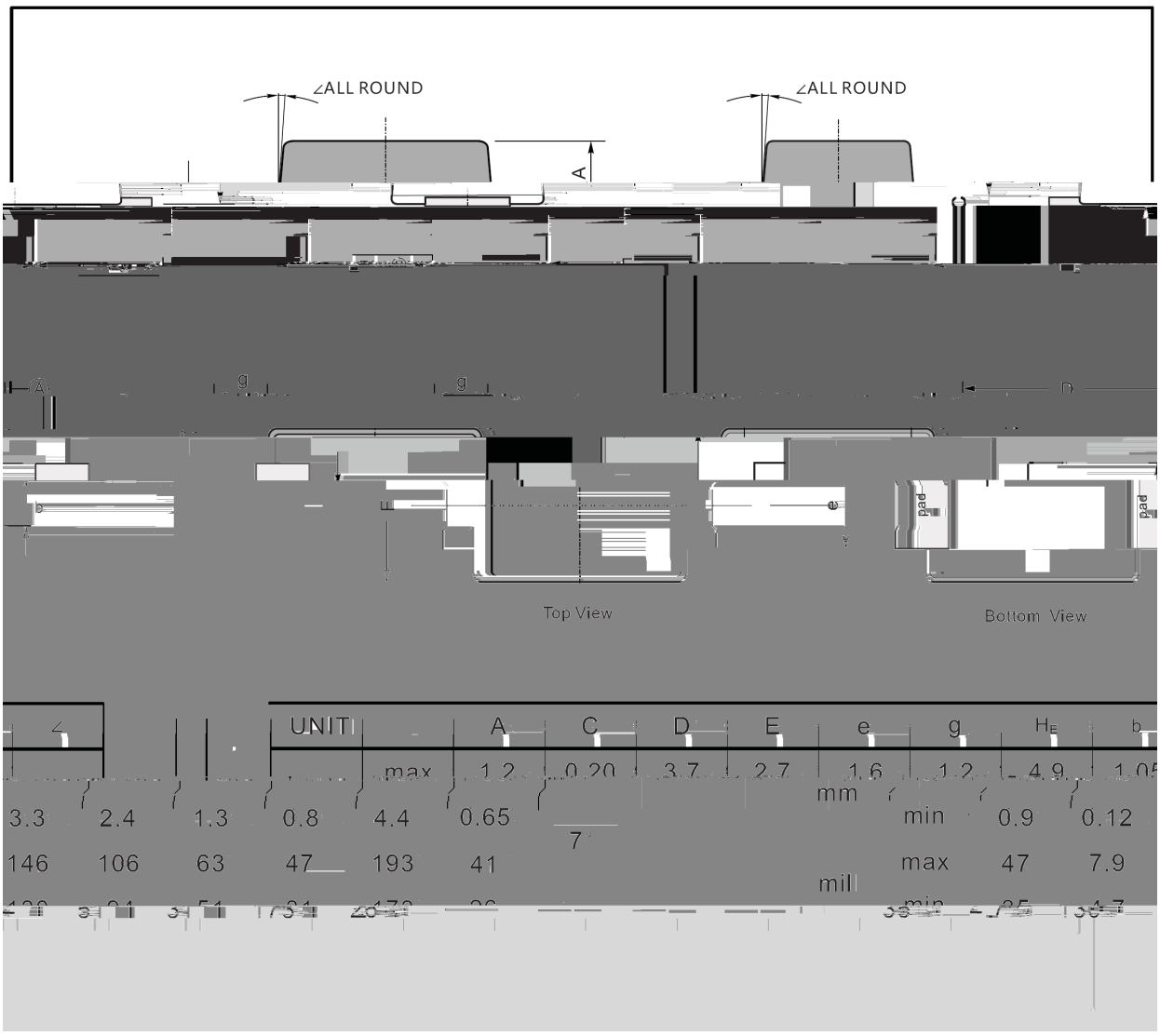
Reverse Voltage (V)

Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



Number of Cycles

Ø =) ¢ / Package Dimensions



∠	UNIT	A	C	D	E	e	g	H_E	b
	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	1.05
	mm								
3.3		2.4	1.3	0.8	4.4	0.65		min	0.9	0.12
							7°			
146		106	63	47	193	41		max	47	7.9
								mil		
								min		

WD t ¢ (x/) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

“ ¢ y

1o ˜ ‰ 150 ‰180 - k 60 ‰90sec;

2o Q 245 r5 - k 4 Ò 5 r0.5sec;

3o D N òi Ò0 , 2 ‰10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

´D /Cª p fl »] / **Resistance to Soldering Heat Test Conditions**

605 r5 - (/ -5.7(Packagling)24286(SPEC.( )]TJ/TT7 1 Tf03.4485 32.3713 TD.0004 Tc-35.65309:6025130